

**Amendments to the Specification:**

Please replace the Abstract with the attached substitute Abstract. For your convenience, a mark-up of the Abstract follows:

~~The present invention is a substrate for forming a patterned thin film by causing a specific fluid to adhere. More particularly, this substrate comprises a pattern formation region that is patterned in a specific shape in order to form a film. This pattern formation region is constituted such that an affinity region having an affinity to the fluid is disposed according to specific rules within a non-affinity region not having an affinity to the fluid. The fluid can be uniformly made to adhere to the required region, without spreading out too much or splitting up, allowing a uniform thin film to be formed.~~ The present application is directed to various methods for forming a patterned thin film on a substrate by causing a specific fluid to adhere. More particularly, this application describes a method for manufacturing a substrate by forming a metal layer on a base, removing a part of the metal layer by supplying energy to form a pattern non-formation region comprised of the metal layer pattern non-formed region and a pattern formation region comprised of a metal layer pattern formed region and a base exposed region, forming a sulfur compound film on the metal layer pattern unformed region and the metal layer pattern formed region by immersing the base in a liquid containing a sulfur compound and forming a thin film pattern on the pattern formation region by applying a fluid to the pattern formation region that exhibits a non-affinity to the sulfur compound film and an affinity to the base.